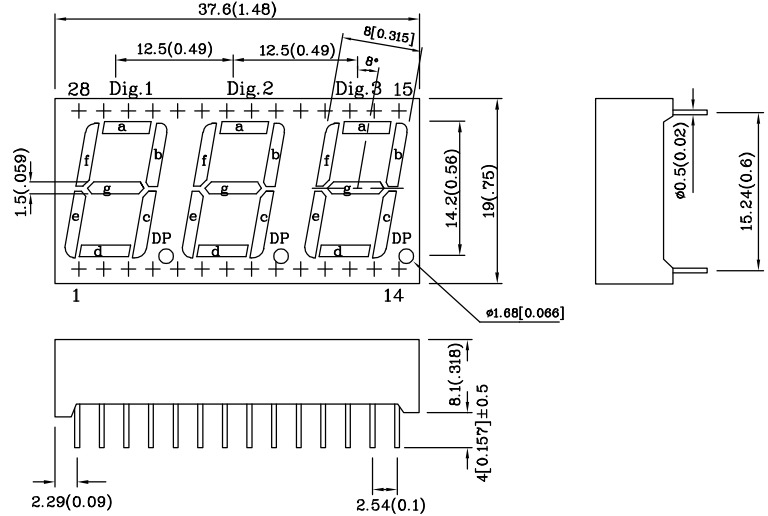
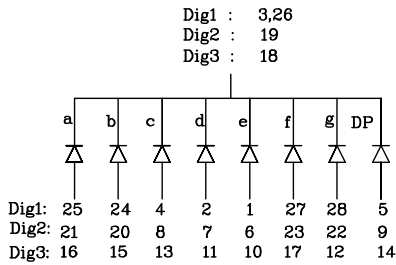


**Features**

- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD: GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



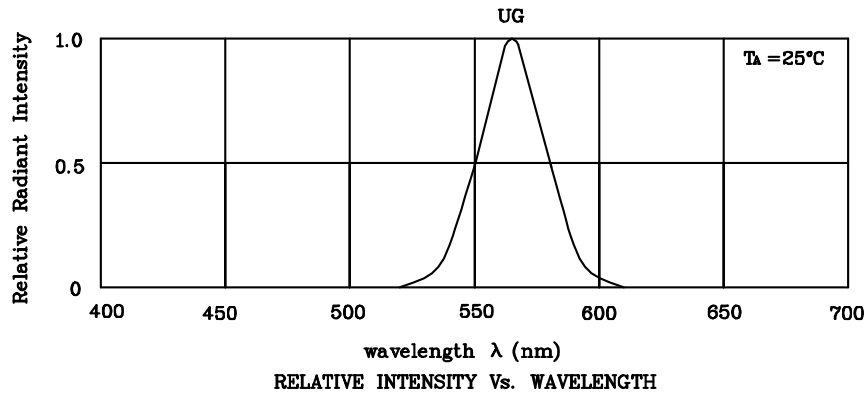
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.

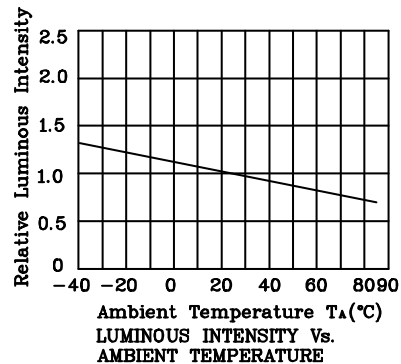
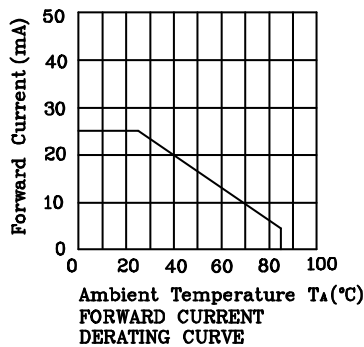
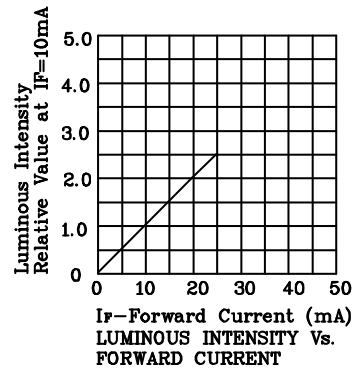
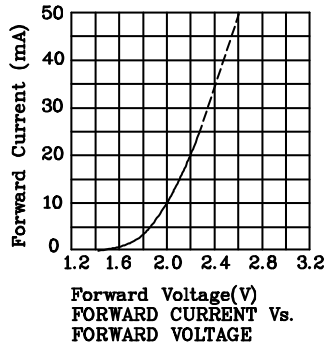
Absolute maximum ratings (TA=25°C)	UG (GaP)	Unit
Reverse Voltage	VR	5 V
Forward Current	IF	25 mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140 mA
Power Dissipation	PT	105 mW
Operating Temperature	TA	-40 ~ +85 °C
Storage Temperature	Tstg	-40 ~ +85 °C
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds	

Operating Characteristics (TA=25°C)	UG (GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	VF	2.0 V
Forward Voltage (Max.) (IF=10mA)	VF	2.5 V
Reverse Current (VR=5V)	IR	10 uA
Wavelength of Peak Emission (IF=10mA)	$\lambda P$	565 nm
Wavelength of Dominant Emission (IF=10mA)	$\lambda D$	568 nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	$\Delta\lambda$	30 nm
Capacitance (VF=0V, f=1MHz)	C	15 pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd	Wavelength nm $\lambda P$	Description
			min.	typ.	
XDUG14C3-A	Green	GaP	1900	10490	565 Common Cathode, Rt. Hand Decimal
Published Date : JUN 01,2005      Drawing No : XDSA1065      V4      Checked : Shin Chi      P.1/3					



◆ UG



Remarks:

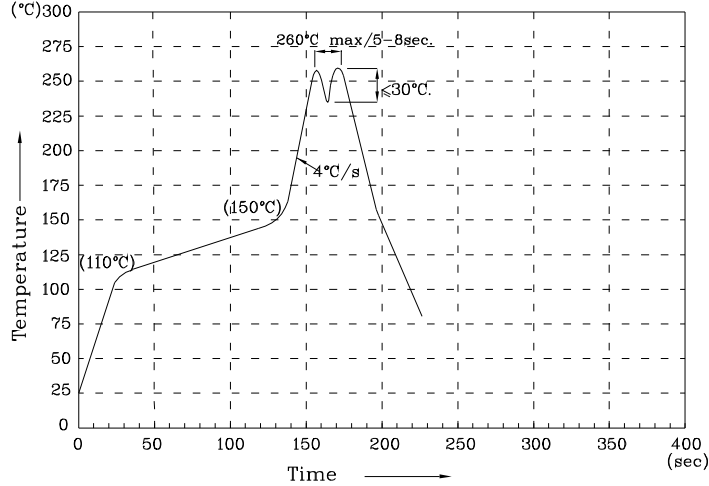
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**XDUG14C3-A**

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.